Product Change Notification: MAAN-05KMXJ752

Date:

12-Oct-2026

Product Category:

CAN Controller

Notification Subject:

CCB 6533.001 Final Notice: Qualification of MMT as a new assembly site for MCP2517FD-H/JHAVAO, MCP2517FDT-H/JHA, MCP2517FDT-H/JHAVAO and MCP2517FD-H/JHA catalog part numbers (CPN) available in 14L VDFN (3x4.5x0.9mm) wettable flank package.

Affected CPNs:

MAAN-05KMXJ752_Affected_CPN_10122026.pdf
MAAN-05KMXJ752_Affected_CPN_10122026.csv

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.
Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of MMT as a new assembly site for MCP2517FD-H/JHAVAO, MCP2517FDT-H/JHA, MCP2517FDT-H/JHAVAO and MCP2517FD-H/JHA catalog part numbers (CPN) available in 14L VDFN (3x4.5x0.9mm) wettable flank package.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change
Assembly Site	ASE Inc. (ASE)	Microchip Technology Thailand (Branch) (MMT)	Yes
Wire Material	Au	Au	No
Die Attach Material	FH-900 (PFAS free)	8006NS (PFAS free)	Yes

Molding Compound Material	G631H	G700LTD	Yes
Lead-Frame Material	C194	A194 *	No
Lead-Frame DAP Surface Prep	Bare Cu	Ag selective	Yes
Lead-Frame Lead-Lock	Yes (Dimple)	Yes (locking hole)	Yes
Lead-Frame Design	See Pre and Post Change Summary Attachment for Comparison.		

Note *: C194, A194 and CDA194 lead-frame materials are the same — it is only a Microchip internal labelling difference.

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying MMT as a new assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 30 November 2026 (date code: 2649)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	October 2026					November 2026				
Work Week	40	41	42	43	44	45	46	47	48	49
Qual Report Availability			x							
Final PCN Issue Date			x							
Estimated Implementation Date										x

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCB# 6533.

Revision History: October 12, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

PCN_MAAN-05KMXJ752 Pre and Post Change_Summary.pdf
PCN_MAAN-05KMXJ752 Qual Report.pdf

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our **PCN home page** select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the **PCN FAQ** section.

If you wish to change your PCN profile, including opt out, please go to the **PCN home page** select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN):

MCP2517FD-H/JHAVAO

MCP2517FDT-H/JHA

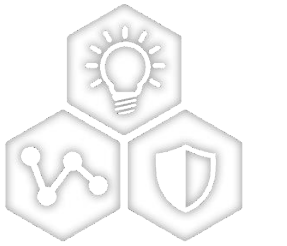
MCP2517FDT-H/JHAVAO

MCP2517FD-H/JHA

CCB 6533.001
Pre and Post Change Summary
PCN #: MAAN-05KMXJ752

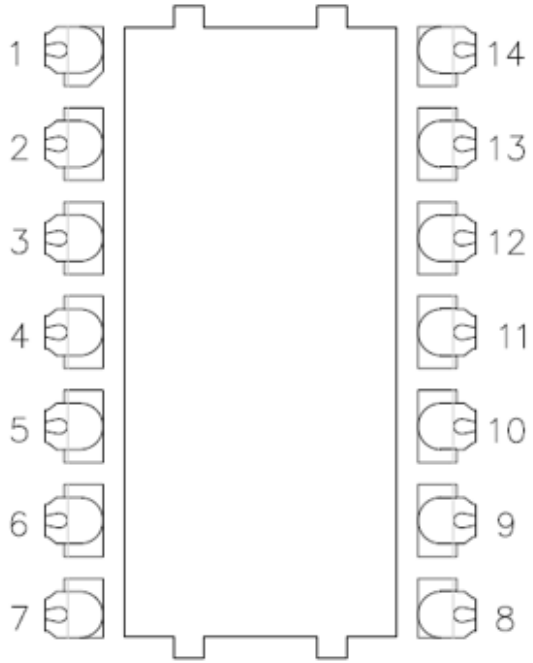


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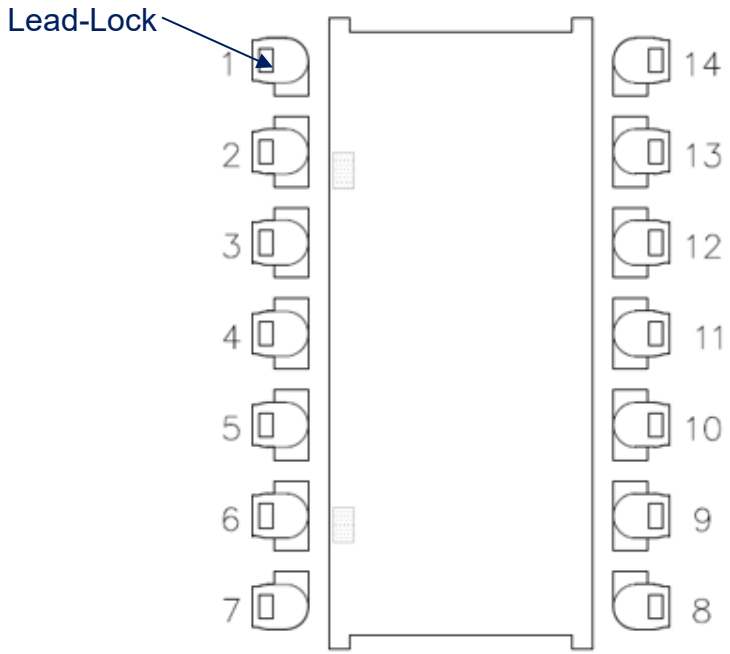
Lead-Frame Comparison

ASE



Lead-Frame Material	C194
DAP Surface Prep	Bare Cu
Lead-lock	Yes (Dimple)

MMT



Lead-Frame Material	A194
DAP Surface Prep	Ag selective
Lead-lock	Yes (locking hole)

Note 1: Mold compound materials fills the leadlock hole, which provides improved protection against moisture penetration along the edge of the leads (pins) of the package.
Note 2: C194, A194 and CDA194 lead-frame materials are the same — it is only a Microchip internal labelling difference.
Note 3: Not to scale.

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Qualification Report Summary

RELIABILITY LABORATORY

PCN #: MAAN-05KMXJ752

Date

October 3, 2024

Qualification of MMT as a new assembly site for MCP2517FD-H/JHAVAO, MCP2517FDT-H/JHA, MCP2517FDT-H/JHAVAO and MCP2517FD-H/JHA catalog part numbers (CPN) available in 14L VDFN (3x4.5x0.9mm) wettable flank package. This is a Q100 Grade 0 qualification.

PACKAGE QUALIFICATION REPORT

Purpose:

Qualification of MMT as a new assembly site for MCP2517FD-H/JHAVAO, MCP2517FDT-H/JHA, MCP2517FDT-H/JHAVAO and MCP2517FD-H/JHA catalog part numbers (CPN) available in 14L VDFN (3x4.5x0.9mm) wettable flank package. This is a Q100 Grade 0 qualification.

CN:	E000209064
QUAL ID:	R2400189
QUAL ID Rev.:	A
MP CODE:	TAGD1JQBBVA1
Part No.:	MCP2518FDT-H/QBBVAO
Bonding No.:	BD-001709 Rev. 01
CCB No.:	6533

Lead Frame

Paddle Size:	75 x 169 mils
Material:	A194
DAP Surface Prep:	Ag
Process:	Etched
Lead Lock:	Yes
Part Number:	10101414
Lead Plating:	Matte Sn

Bond Wire

Wire:	Au wire

Die Attach Material

Epoxy:	8006NS

Mold Compound

Mold Compound:	G700LTD

Package

Type:	14L VDFN-WFS
Package Size:	3 x 4.5 mm

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MMT-244101783.000	TC08924219232.110	2402K0Q
MMT-244101784.000	TC08924219232.110	2402Q0J
MMT-244101785.000	TC08924219232.110	2402Q28

Result: **Pass**

Conclusion:

14L VDFN-WFS (3x4.5 mm) assembled by MMT pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	**Electrical Test:** +25°C, 85°C, 125°C and 150°C **System:** J750	JESD22-A113	693(0)	0/693	Pass	Good Devices
	Bake 150°C, 24 hrs. **System:** CHINEE	JIP/IPC/JEDEC J-STD-020E	693			
	85°C/85%RH Moisture Soak 168 hrs. **System:** TABAI ESPEC Model PR-3SPH		693			
	3x Convection-Reflow 265°C max **System:** Vitronics Soltec MR1243		693			
	Electrical Test: +25°C, 85°C, 125°C and 150°C **System:** J750		693(0)	0/693	Pass	
Temp Cycle	**Stress Condition:** -55°C to +150°C, 1500 Cycles **System:** TABAI ESPEC TSA-70H	JESD22-A104		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +85°C,125°C and 150°C **System:** J750		231(0)	0/231	Pass	77 units / lot
UNBIASED-HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. **System:** HAST 6000X	JESD22-A118		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C **System:** J750		231(0)	0/231	Pass	77 units / lot
HAST	**Stress Condition:** +130°C/85%RH, 96 hrs. Bias Volt: 5.5 Volts **System:** HAST 6000X	JESD22-A110		0/231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C, 85°C, 125°C and 150°C **System:** J750		231(0)	0/231	Pass	77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	**Stress Condition:** Bake 175°C, 1000 hrs. **System:** TPS Bake Oven	JESD22-A103		0/45		45 units
	Electrical Test: +25°C, 85°C, 125°C and 150°C **System:** J750		45(0)	0/45	Pass	
Bond Strength Data Assembly	Wire Pull (>2.50 grams)	Mil. Std. 883-2011	30(0) Wires	0/30	Pass	
	Bond Shear (>15.00 grams)	CDF-AEC-Q100-001	30(0) bonds	0/30	Pass	